

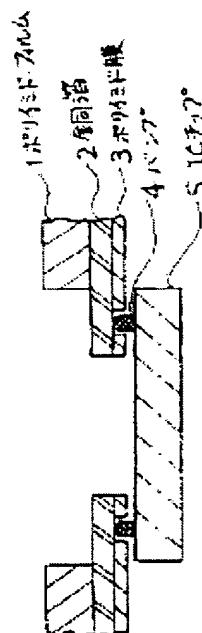
ASSEMBLY TAPE OF INTEGRATED CIRCUIT DEVICE

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- **international:** H01L21/60
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Abstract of JP1205544

PURPOSE: To eliminate the contact of a lead wire and a defect due to a short circuit and to change a position of a bonding part by forming an insulating film on the surface of a conductor foil sheet excluding a pad part and a part to be bonded to an external lead.

CONSTITUTION: A copper foil sheet 2 is formed on the surface of a polyimide film 1; a punched hole is made in the film 1; a lead wire is projected inside the punched hole by the copper foil sheet 2. A polyimide film 3 is coated and formed on the main surface of the copper foil sheet 2 excluding a part where a bump 4 of an IC chip 5 is to be bonded. By this setup, the contact of a lead wire and a defect due to a short circuit are eliminated; a position of a bonding part can be changed.



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